# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Toshiyuki HIROSE	05/07/2007
Hideki NONOYAMA	05/07/2007
Osamu NAKAMURA	05/07/2007
Akira ITOU	05/07/2007
Yoshinori SAITO	05/07/2007

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#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11747464

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PATENT REEL: 019282 FRAME: 0083

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Total Attachments: 2 source=307539USAssignment#page1.tif source=307539USAssignment#page2.tif

PATENT REEL: 019282 FRAME: 0084 Docket Number: \_\_\_\_\_

WHEREAS, I, as a below named inventor, residing at to only one name is listed below) or a joint inventor (if plural names are list HELICAL SCAN TYPE MAGNETIC TAPE REPRODUCTION APPARAREPRODUCTION METHOD	ted below) of certain new and useful improvements in
for which application for Letters Patent of the United States of America w and address;	as executed by me on the date indicated next to my nam
AND WHEREAS, Sony Corporation, a Japanese corporation, Japanese co	g all interest in, to and under said invention,
NOW THEREFORE, in consideration of the sum of One the receipt and sufficience of which are hereby acknowledged, I, as a sole hereby assign, sell and transfer unto the said ASSIGNEE, its successors, as interest in the said invention, said application, including any divisions and Patent of the United States, and countries foreign thereto, which may be grarights and/or convention rights under the International Convention for the Pro Relating to Patents, Designs and Industrial Models, and any other internat adheres, and to any other benefits accruing or to accrue to me with respect patents in the United States and countries foreign thereto, and I hereby authorized United States Letters Patent to said ASSIGNEE, as the assignee of the	or joint inventor as indicated below, besigns, and legal representatives, the entire right, title and continuations thereof, and in and to any and all Letter anted for said invention, and in and to any and all priority of tection of Industrial Property, Inter-American Convention ional agreements to which the United States of Americat to the filing of applications for patents or securing or prize and request the Commissioner of Patents to issue the
And I further agree to execute all necessary or desirable and law ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and le and without further remuneration, in order to perfect title in said invention applications and Letters Patent of the United States and countries foreign to	gal representatives may from time-to-time present to mon, modifications, and improvements in said invention
And I further agree to properly execute and deliver and without fur papers for application for foreign patents, for filing subdivisions of said ap reissues of any Letters Patent which may be granted for my aforesaid invent prepare at its own expense;	plication for patent, and or, for obtaining any reissue o
And I further agree that ASSIGNEE will, upon its request, be pr relating to said application, said invention and said Letters Patent and lega accessible to me and will testify as to the same in any interference or litigate	l equivalents in foreign countries as may be known and
And I hereby covenant that no assignment, sale, agreement or encu would conflict with this assignment and sale.	mbrance has been or will be made or entered into whic
And I hereby authorize and request my attorney(s) of record in this this application in the spaces that follow: Serial Number:	
This assignment executed on the dates indicated below.	
Toshiyuki HIROSE	
Name of first or sole inventor	Execution date of U.S. Patent Applicatio
Kanagawa, Japan	
Residence of first or sole inventor	
Signature of first or sold inventor	May 7 200 7 Date of this assignment
Signature of first or sold inventor	Date of this assignmen

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Hideki NONOYAMA	
Name of second inventor	Execution date of U.S. Patent Application
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Residence of second inventor	
Signature of second inventor	May 7 2007
Signature of second inventor	Date of this assignment
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Osamu NAKAMURA	
Name of third inventor	Execution date of U.S. Patent Application
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Yoshinori Saito	May 7 2007
ignature of fifth inventor	Date of this assignment

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**RECORDED: 05/11/2007**